

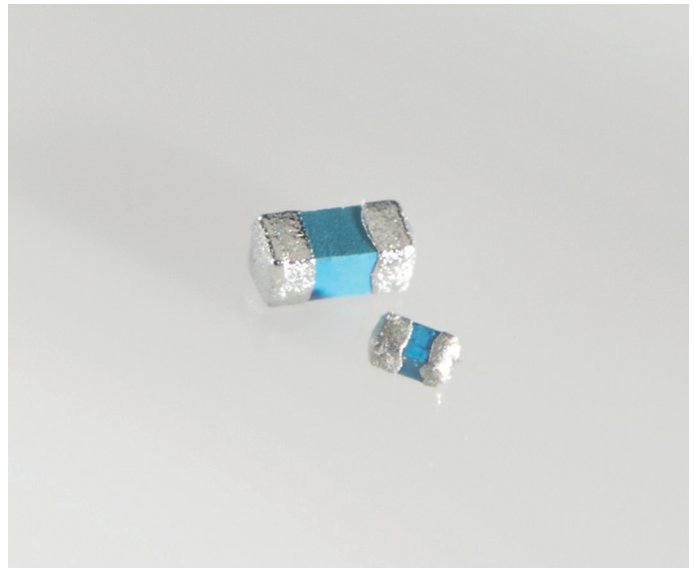
CHIPSESD DEVICES

Littelfuse's ChipSESD family of Silicon ESD devices, available in EIA-0201 and EIA-0402 sized rectangular SMT passive component packages, can help protect electronic circuits against damage from electrostatic discharge (ESD) events.

The SESD0201P1BN-0400-090, 0201-sized ChipSESD device's miniature footprint (0.6mm x 0.3mm x 0.3mm) is approximately 70% smaller than prior-generation devices. This offers designers flexibility in space constrained applications.

The ChipSESD devices are high-capacitance, bi-directional devices that can be used for low-speed generic interfaces such as keypads, power buttons, speakers and microphone ports in a portable electronics. The bi-directional operation eliminates orientation constraints and the need for polarity inspections. The surface mount technology (SMT) passive component package allows the devices to be easily installed onto the printed circuit board using the standard PCB assembly process. Once soldered onto the boards, the ChipSESD's solder fillets at the end terminals can easily be visually inspected.

The ChipSESD devices offer 10kV contact and 16kV air discharge protection per the IEC61000-4-2, level 4 standard with a surge rating of 2A under 8x20Qs pulse.



BENEFITS

- Silicon ESD devices in an EIA-0201 and EIA-0402 sized rectangular SMT passive component package
- Bi-directional operation eliminates orientation constraints
- Standard PCB assembly and rework process
- ESD protection in space-constrained portable electronics and mobile handsets
- Helps protect electronic circuits against damage from ESD
- Assists equipment to pass IEC61000-4-2, level 4 testing

FEATURES

- Input capacitance -4.0pF (typ) & 4.5pF (typ)
- Low leakage current - 1.0 μ A (max)
- Low working reverse voltage - 6.0V (max)
- Capable of withstanding numerous ESD strikes
- RoHS compliant
- Halogen free
(refers to: Br \geq 900ppm, Cl \geq 900ppm, Br+Cl \geq 1500ppm)

APPLICATIONS

- Mobile phones and portable electronics
- Digital cameras and camcorders
- Notebooks, set top boxes, motherboards
- USB 2.0 and computer I/O ports
- Applications requiring high ESD performance in a small package

Table CE1 – Maximum Ratings

Part Number	IEC61000-4-2, level 4 (ESD Withstand)		Temperature	
	Contact (kV)	Air (kV)	Operating (°C)	Storage (°C)
SESD0201P1BN-0400-090	±10*	±16	-40 to +125	-40 to +125
SESD0402P1BN-0450-090	±10*	±16	-40 to +125	-40 to +125

Table CE2 – Electrical Characteristics @ T=25°C

Part Number	Input Capacitance*		Leakage Current (max) I _L @ V _{RWM} = 6.0V (µA)	Breakdown Voltage (min) V _{br} @ I _T [†] = 1mA (V)	Working Reverse Voltage V _{RWM} @ peak (V)	Clamping Voltage (typ) V _{CL} @ I _{pp} =2A, tp=(8/20µs) (V)*
	Typ (pF)	Max (pF)				
SESD0201P1BN-0400-090	4.0	5.0	1.0	9.0	6.0	+10.0
SESD0402P1BN-0450-090	4.5	5.5	1.0	9.0	6.0	+10.0

* @ Vr=0V, f=1MHz

† V_{br} is measured at test current I_T

Figure CE1 – ESD Clamping Voltage - 8kV Contact

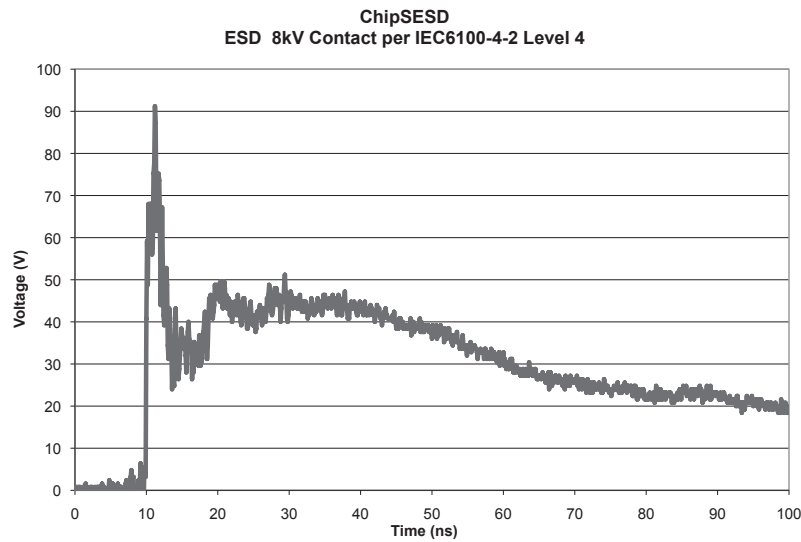
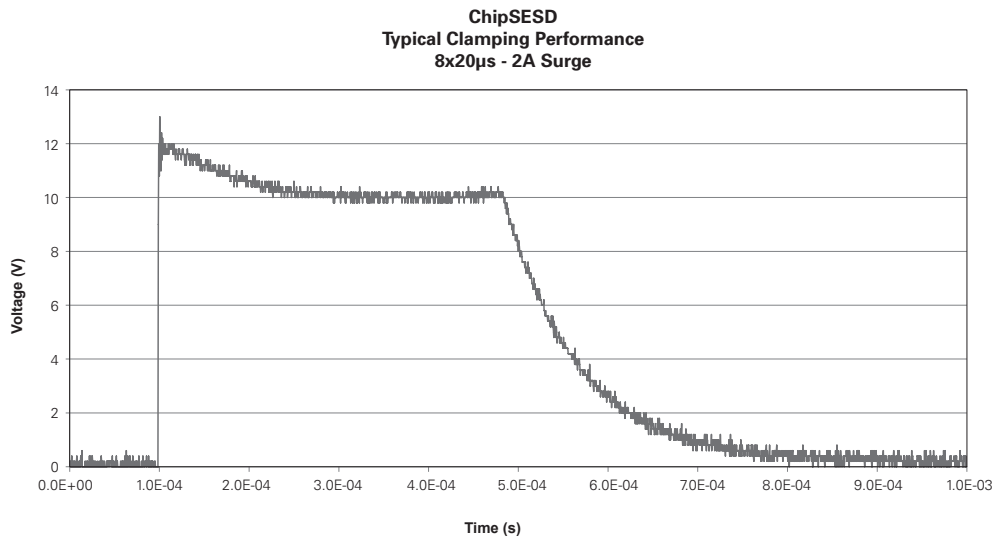


Figure CE2 – ESD Clamping Voltage - 8x20µs, 2A Surge



ChipSESD Devices

Table CE3 - Dimensions in Millimeters and (Mils)*

Part Number	A	B	C	D	Figure
SESD0201P	0.60 ± 0.05	0.30 ± 0.05	0.30 ± 0.05	0.21 ± 0.07	CE3
	(23.62 ± 2.00)	(11.81 ± 2.00)	(11.81 ± 2.00)	(8.27 ± 2.80)	
SESD0402P	1.10 ± 0.10	0.50 ± 0.10	0.50 ± 0.10	0.25 ± 0.15	CE3
	(43.31 ± 0.40)	(19.69 ± 4.00)	(19.69 ± 4.00)	(9.84 ± 6.00)	

* Round off approximation

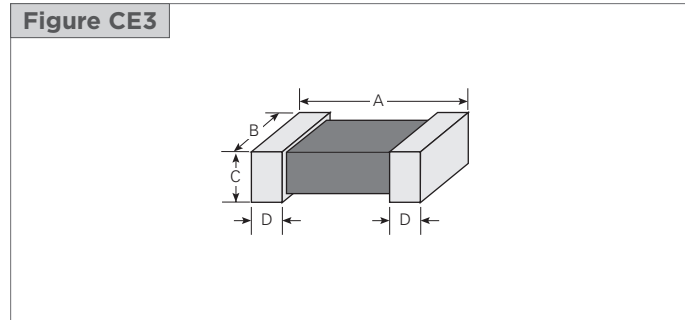


Table CE4 - PCB Pad Layout in Millimeters and (Mils)*

Part Number	L	S	W	Figure
SESD0201P	0.28 ± 0.01	0.19 ± 0.01	0.30 ± 0.01	CE4
	(11.00 ± 0.40)	(7.50 ± 0.40)	(11.80 ± 0.40)	
SESD0402P	0.61 ± 0.05	0.52 ± 0.05	0.50 ± 0.05	CE4
	(24.00 ± 2.00)	(21.00 ± 2.00)	(20.00 ± 2.00)	

* Round off approximation

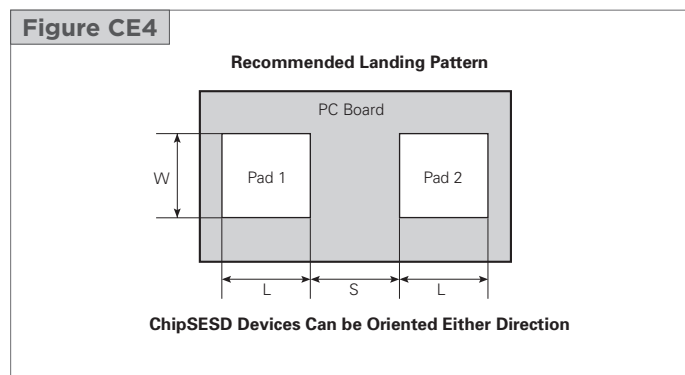


Table CE5 – Tape Specifications

Tape Dimension EIA Mark	SESD0201P1BN-0400-090	SESD0402P1BN-0450-090
	Dimension (mm)	Dimension (mm)
A	0.35 ± 0.02	0.58 ± 0.03
B	0.67 ± 0.02	1.20 ± 0.03
D	1.55 ± 0.05	1.55 ± 0.05
E	1.75 ± 0.05	1.75 ± 0.05
F	3.50 ± 0.05	3.50 ± 0.05
W	8.00 ± 0.10	8.00 ± 0.10
P ₀	4.00 ± 0.10	4.00 ± 0.10
P ₁	2.00 ± 0.05	2.00 ± 0.05
P ₂	2.00 ± 0.05	2.00 ± 0.05
T	0.42 ± 0.03	0.60 ± 0.03

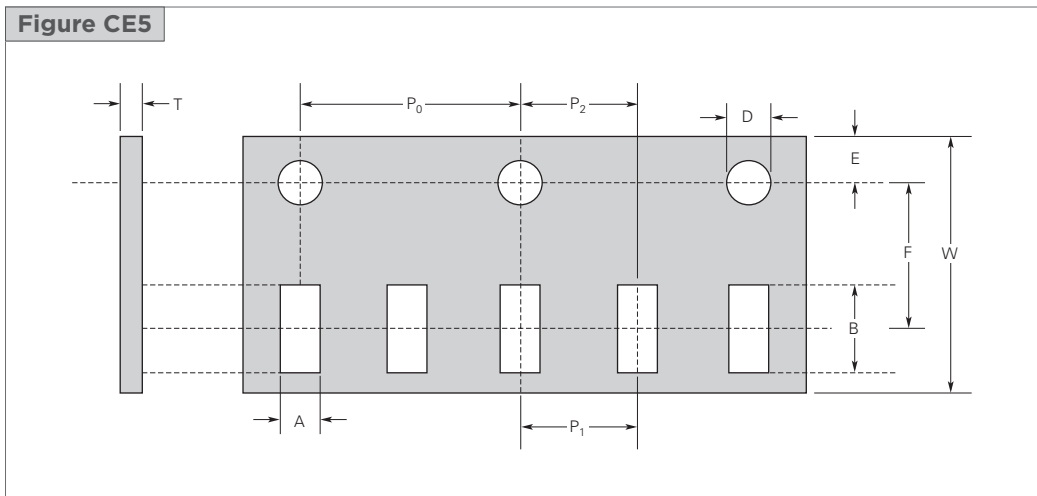
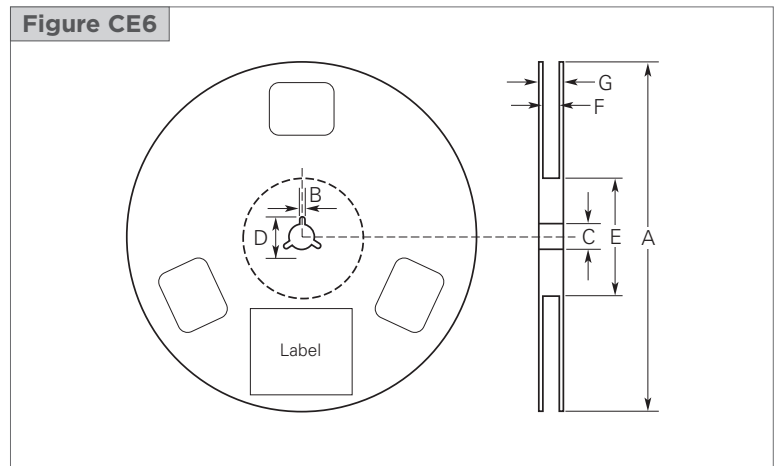


Table CE6 – Reel Specifications

Reel Dimension EIA Mark	Dimension (mm)
A	178.0 ± 2.0
B	2.0 ± 0.5
C	13.0 ± 0.5
D	21.0 ± 0.8
E	62.0 ± 1.5
F	9.0 ± 0.5
G	13.0 ± 1.0

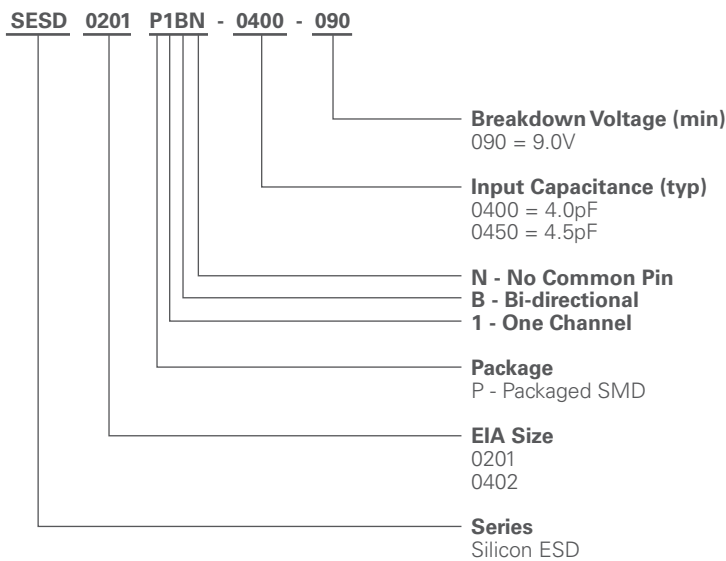


ChipSESD Devices

Definition of Terms

I_L	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Working Peak Reverse Voltage
V_{br}	Breakdown Voltage @ I_T
I_T	Test Current
V_{CL}	Clamping Voltage

Part Numbering System



Notice:

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